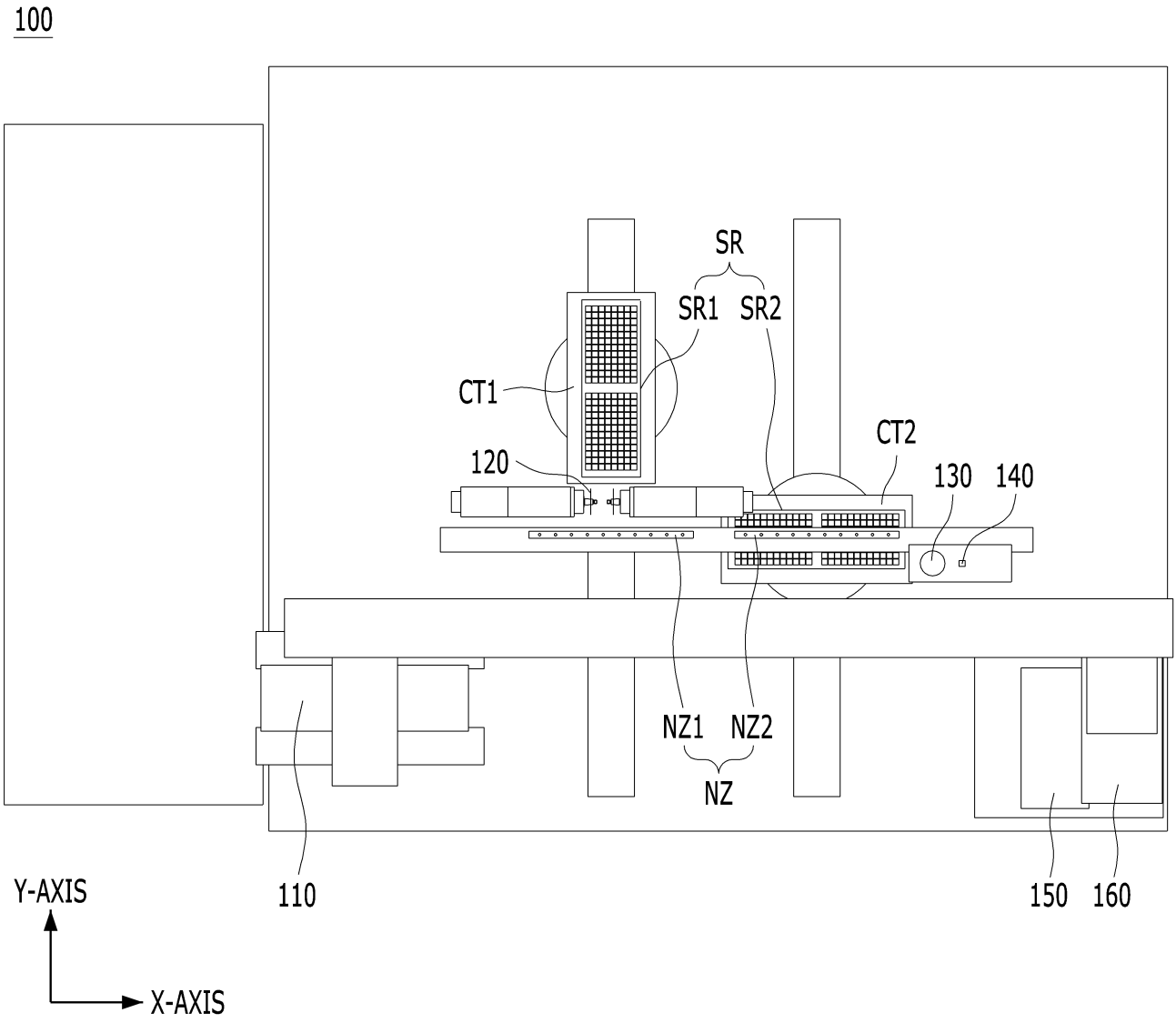

100
SR
SR1
SR2
CT1
CT2
120
130
140
NZ1
NZ2
NZ
110
150
160
Y-AXIS
X-AXIS

FIG. 1

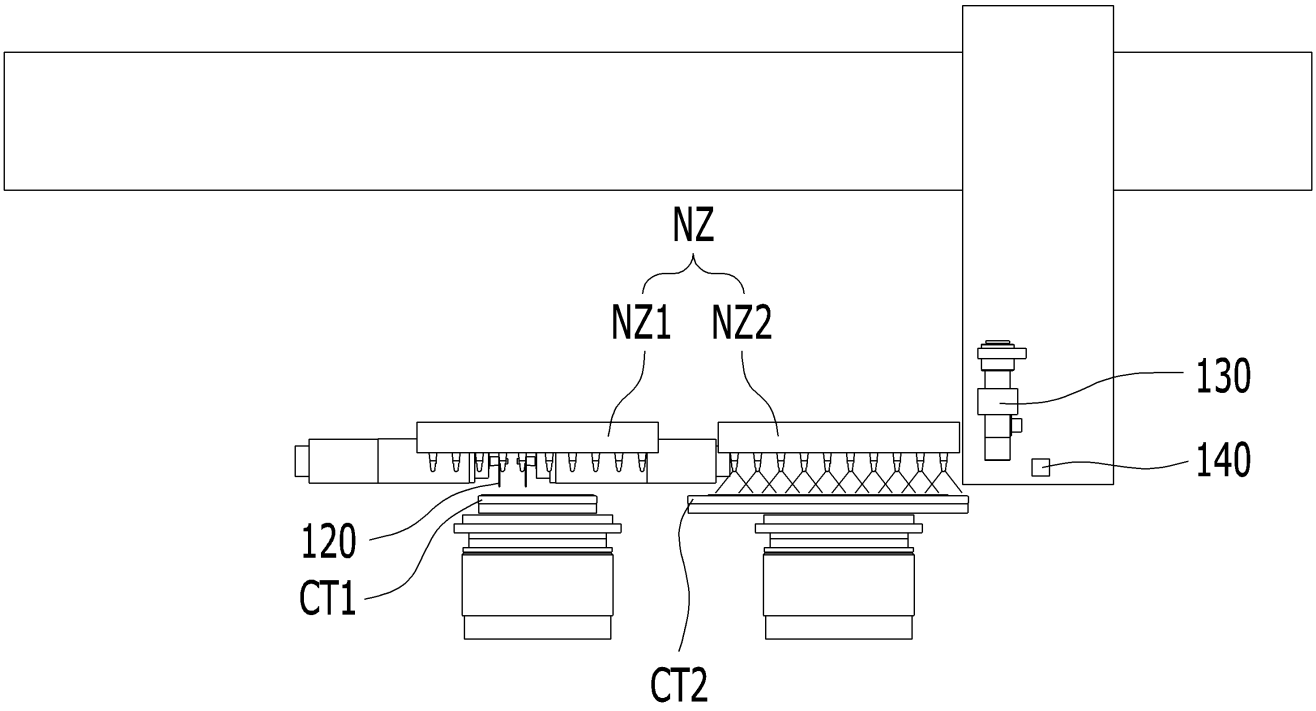


FIG. 2

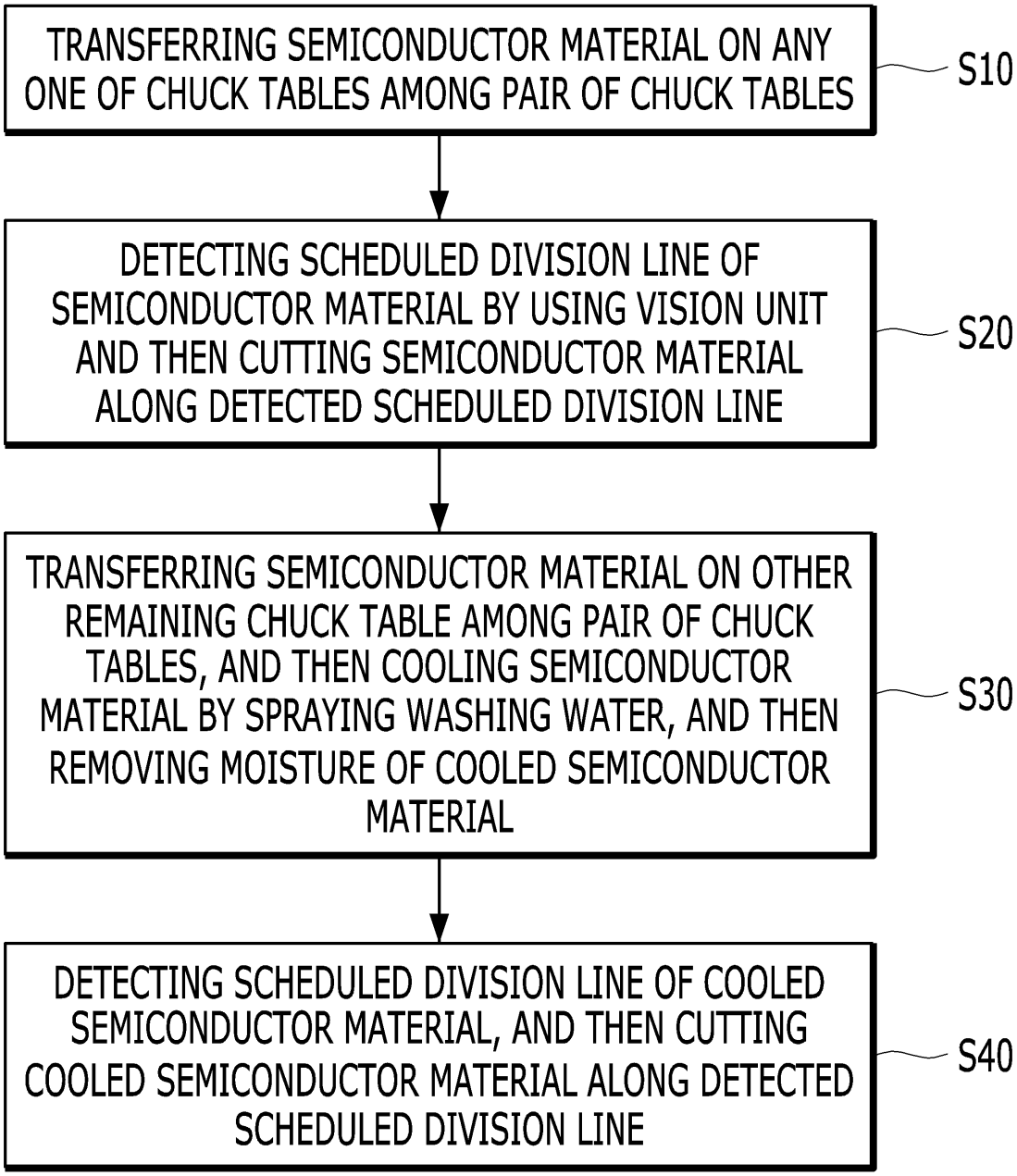

TRANSFERRING SEMICONDUCTOR MATERIAL ON ANY ONE OF CHUCK TABLES AMONG PAIR OF CHUCK TABLES
S10
DETECTING SCHEDULED DIVISION LINE OF SEMICONDUCTOR MATERIAL BY USING VISION UNIT AND THEN CUTTING SEMICONDUCTOR MATERIAL ALONG DETECTED SCHEDULED DIVISION LINE
S20
TRANSFERRING SEMICONDUCTOR MATERIAL ON OTHER REMAINING CHUCK TABLE AMONG PAIR OF CHUCK TABLES, AND THEN COOLING SEMICONDUCTOR MATERIAL BY SPRAYING WASHING WATER, AND THEN REMOVING MOISTURE OF COOLED SEMICONDUCTOR MATERIAL
S30
DETECTING SCHEDULED DIVISION LINE OF COOLED SEMICONDUCTOR MATERIAL, AND THEN CUTTING COOLED SEMICONDUCTOR MATERIAL ALONG DETECTED SCHEDULED DIVISION LINE
S40

FIG. 3